

## N and P-Channel Enhancement Mode Power MOSFET

### Description

The HM4618A uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

### General Features

#### ● P-Channel

$V_{DS} = -40V, I_D = -13A$

$R_{DS(ON)} < 15m\Omega @ V_{GS} = -10V$

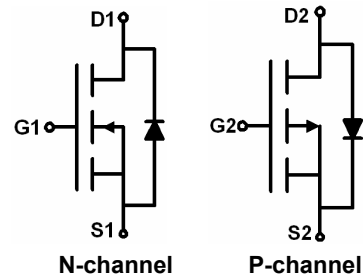
$R_{DS(ON)} < 18m\Omega @ V_{GS} = -4.5V$

#### ● N-Channel

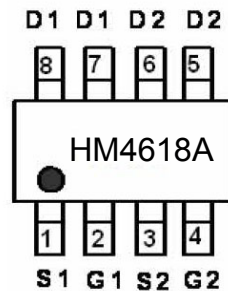
$V_{DS} = 40V, I_D = 15A$

$R_{DS(ON)} < 13m\Omega @ V_{GS} = 10V$

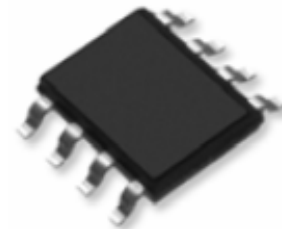
- High power and current handling capability
- Lead free product is acquired
- Surface mount package



Schematic diagram



Marking and pin assignment



SOP-8 top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM4618A	HM4618A	SOP-8	Ø330mm	12mm	2500 units

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter		Symbol	P-Channel	N-Channel	Unit
Drain-Source Voltage		$V_{DS}$	-40	40	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current	$T_A = 25^\circ C$	$I_D$	-13	15	A
	$T_A = 70^\circ C$		-9	10	
Pulsed Drain Current <sup>(Note 1)</sup>		$I_{DM}$	50	50	A
Maximum Power Dissipation	$T_A = 25^\circ C$	$P_D$	2.5	3	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 To 150	-55 To 150	$^\circ C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	P-Ch	62.5	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	N-Ch	62.5	$^{\circ}\text{C/W}$

## P-CH Electrical Characteristics ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-40	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-40V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.3	-2	-2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-12A$	-	12	15	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-15V, I_D=-10A$	35	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	$C_{iss}$	$V_{DS}=-20V, V_{GS}=0V,$ $F=1.0MHz$	-	2800	-	PF
Output Capacitance	$C_{oss}$		-	320	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	220	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-20V, R_L=2\Omega$ $V_{GS}=-10V, R_{GEN}=6\Omega$	-	11	-	nS
Turn-on Rise Time	$t_r$		-	75	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	89	-	nS
Turn-Off Fall Time	$t_f$		-	35	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-20V, I_D=-12A,$ $V_{GS}=-10V$	-	40	-	nC
Gate-Source Charge	$Q_{gs}$		-	6	-	nC
Gate-Drain Charge	$Q_{gd}$		-	12	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=-12A$	-	-	1.2	V
Diode Forward Current (Note 2)	$I_S$		-	-	-13	A

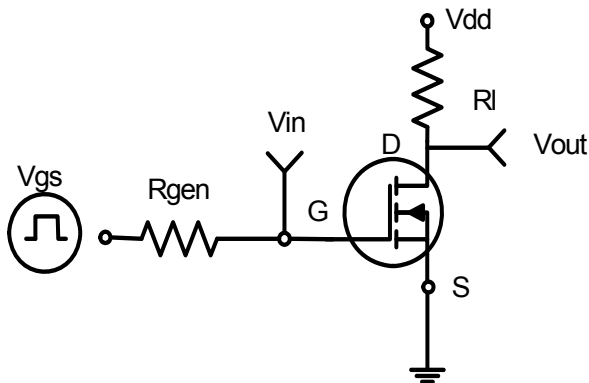
## N-CH Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	40	45	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.6	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =15A	-	7.3	13	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =15A	15	-	-	S
Dynamic Characteristics <sup>(Note4)</sup>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, F=1.0MHz	-	1800	-	PF
Output Capacitance	C <sub>OSS</sub>		-	280	-	PF
Reverse Transfer Capacitance	C <sub>RSS</sub>		-	190	-	PF
Switching Characteristics <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =20V, I <sub>D</sub> =2A, R <sub>L</sub> =1Ω V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω	-	6.4	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	17.2	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	29.6	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	16.8	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =15A, V <sub>GS</sub> =10V	-	29		nC
Gate-Source Charge	Q <sub>gs</sub>		-	4.5		nC
Gate-Drain Charge	Q <sub>gd</sub>		-	6.4		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =10A	-		1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>S</sub>		-	-	15	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = 15A di/dt = 100A/μs <sup>(Note3)</sup>	-	29	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	26	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

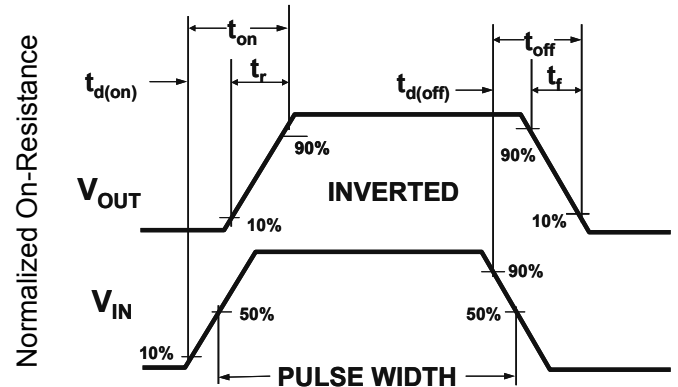
### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

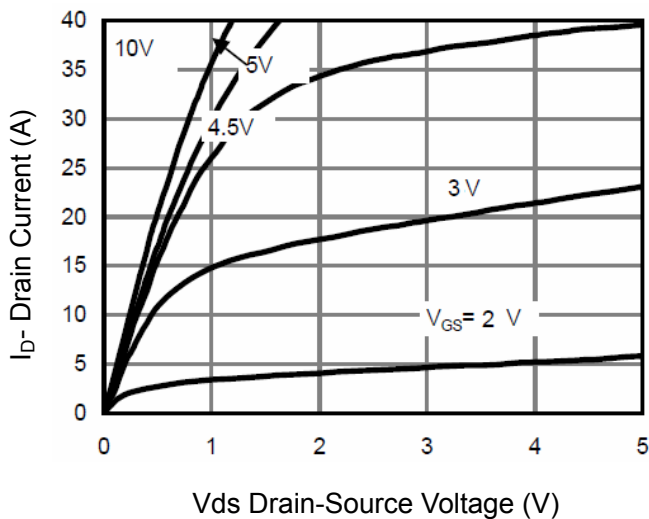
## P- Channel Typical Electrical and Thermal Characteristics (Curves)



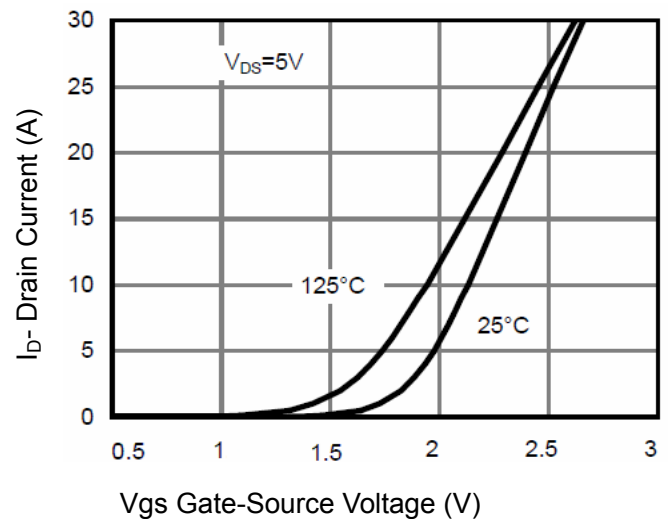
**Figure 1: Switching Test Circuit**



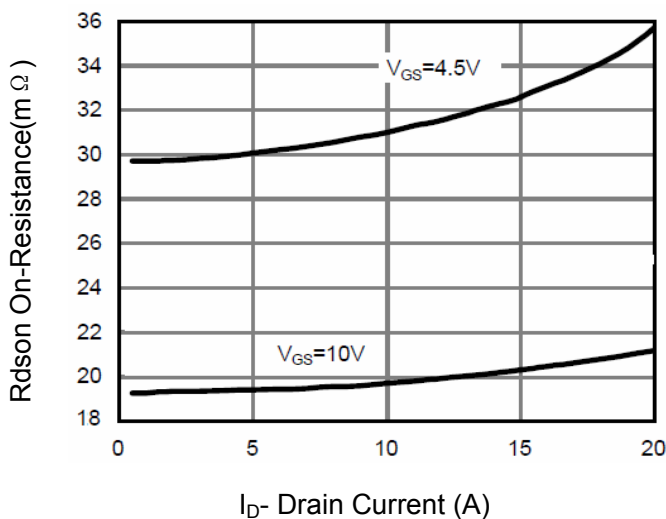
**Figure 2: Switching Waveforms**



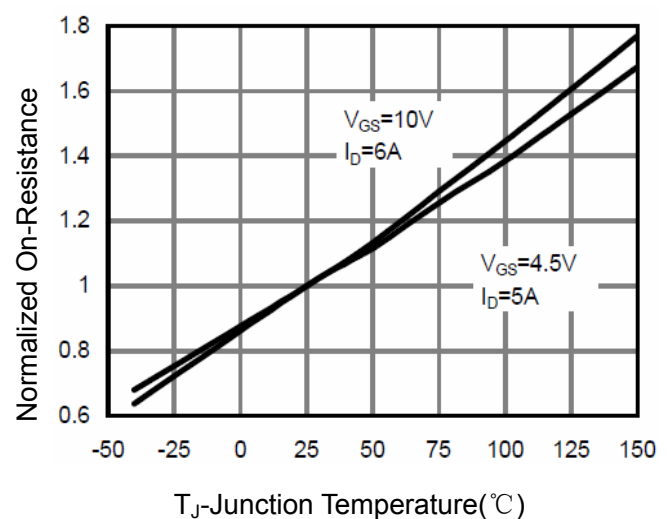
**Figure 3 Output Characteristics**



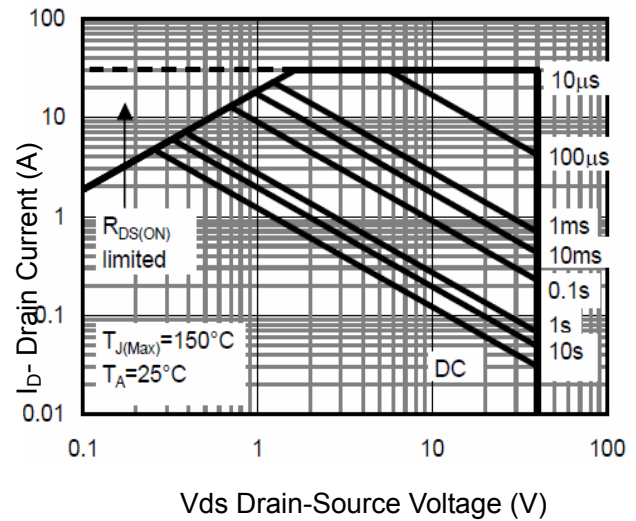
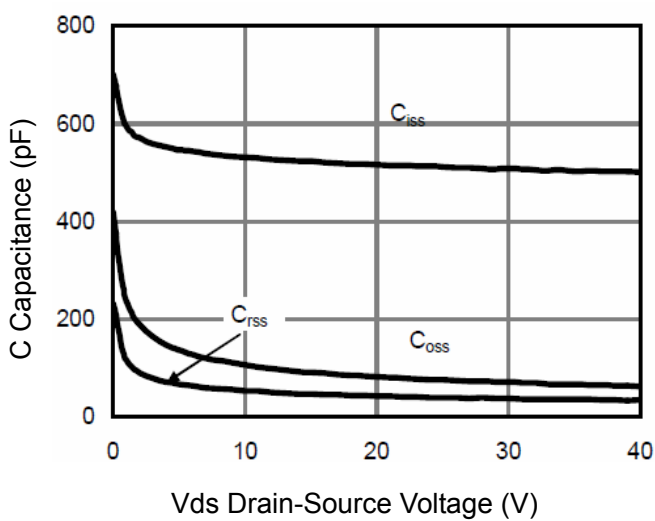
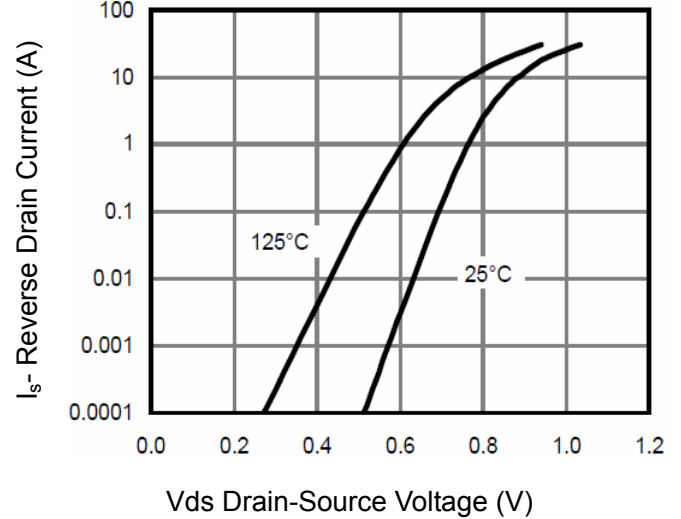
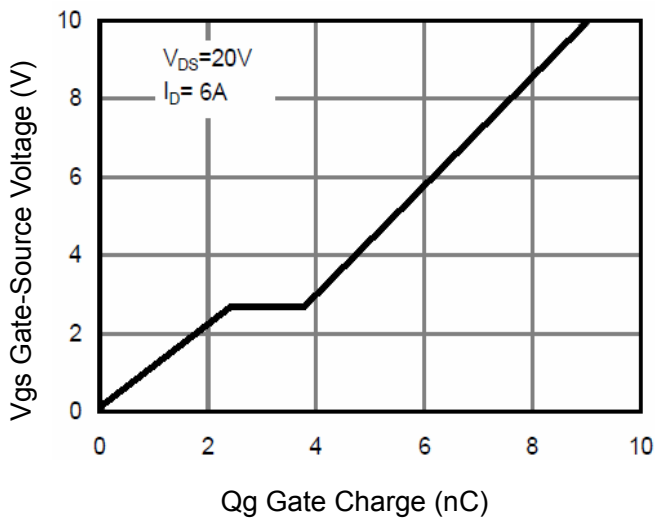
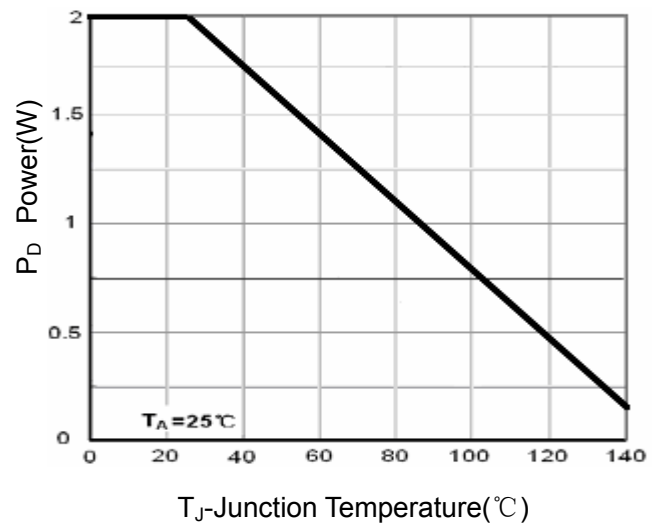
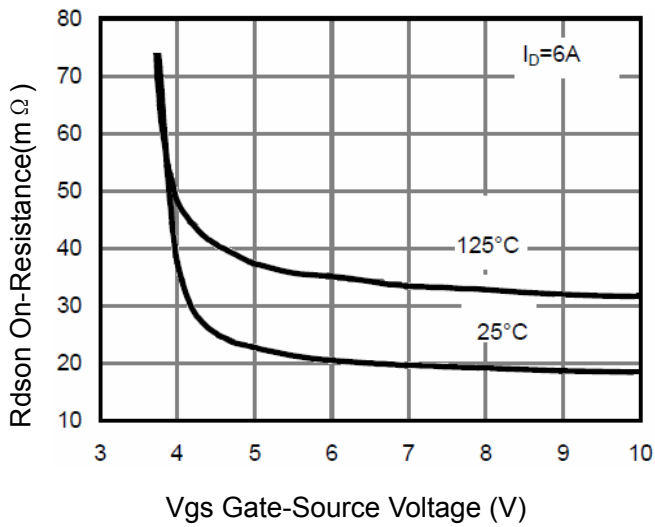
**Figure 4 Transfer Characteristics**

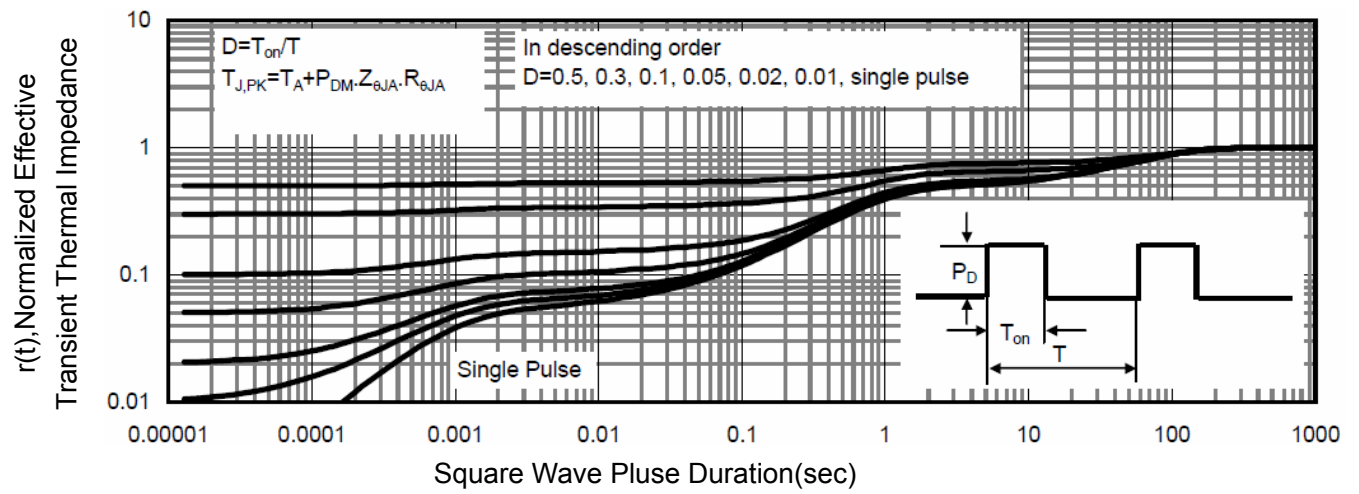


**Figure 5 Drain-Source On-Resistance**



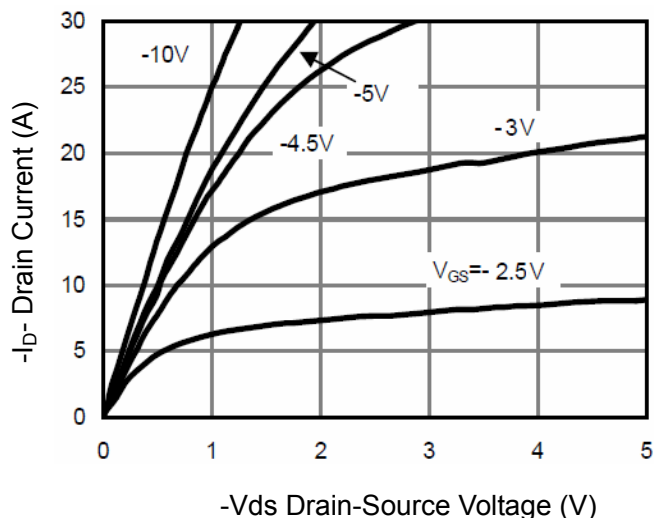
**Figure 6 Drain-Source On-Resistance**



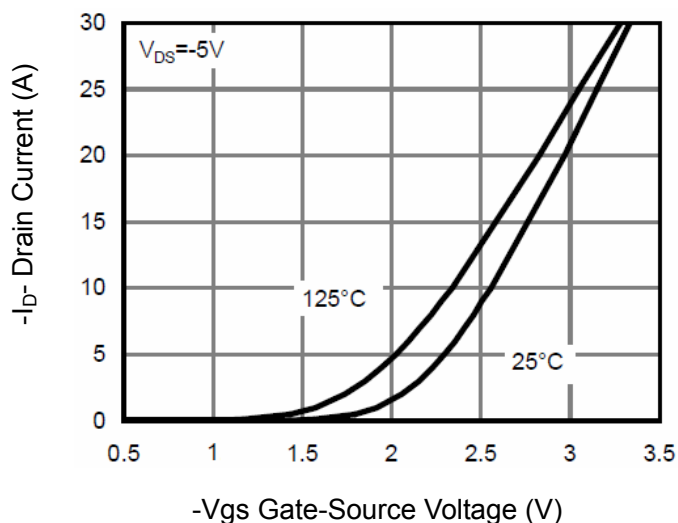


**Figure 13 Normalized Maximum Transient Thermal Impedance**

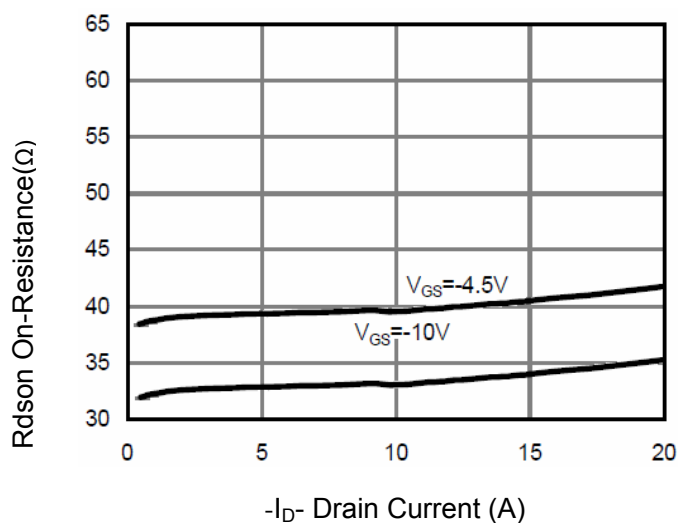
## N- Channel Typical Electrical and Thermal Characteristics (Curves)



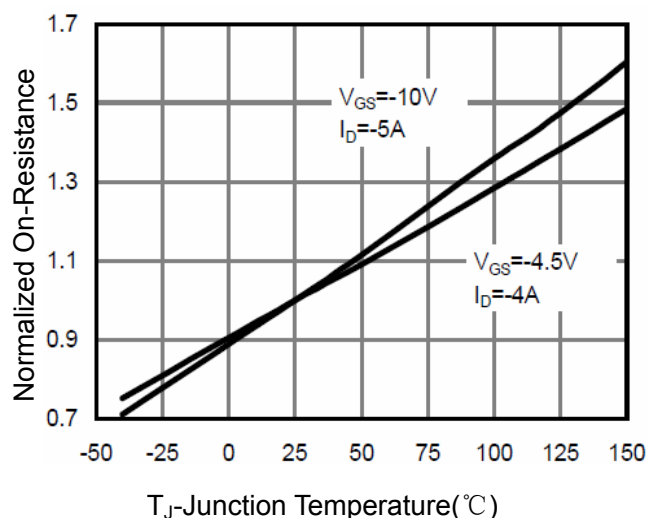
**Figure 1 Output Characteristics**



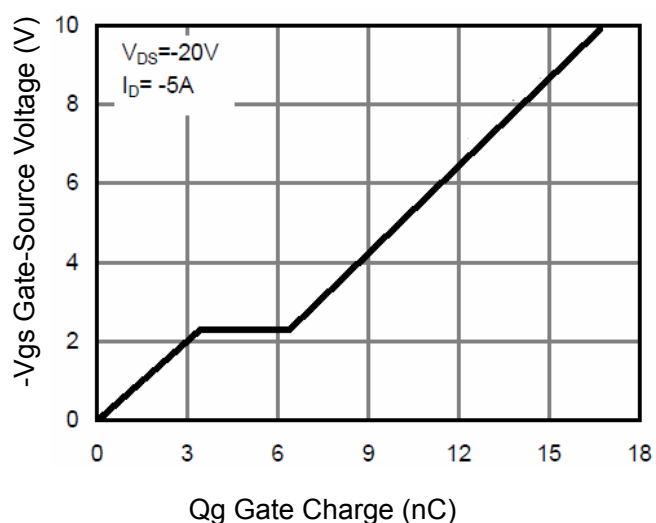
**Figure 2 Transfer Characteristics**



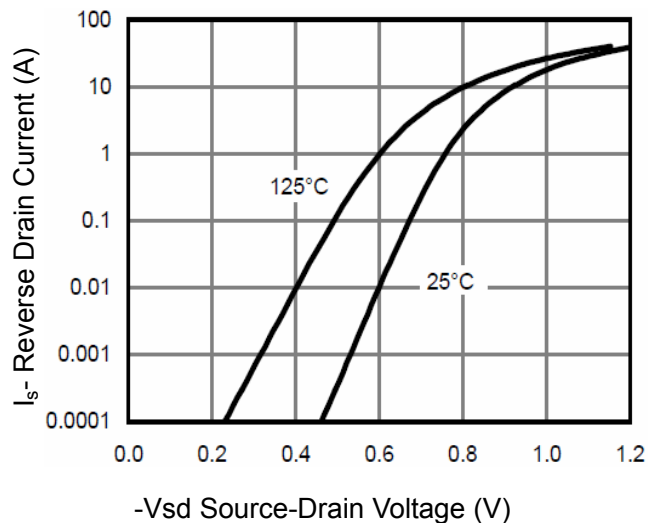
**Figure 3 Rdson- Drain Current**



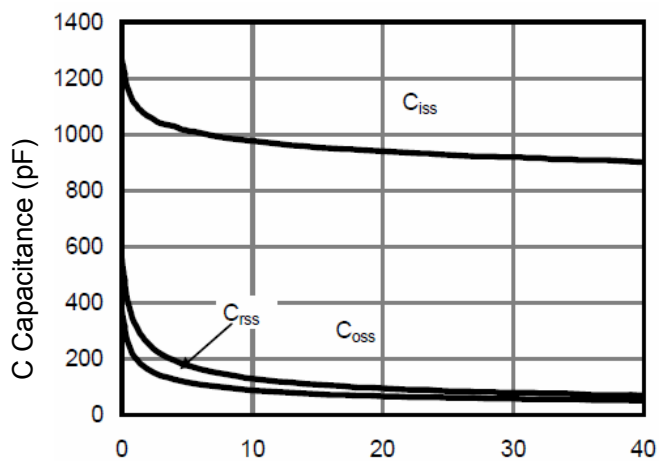
**Figure 4 Rdson-Junction Temperature**



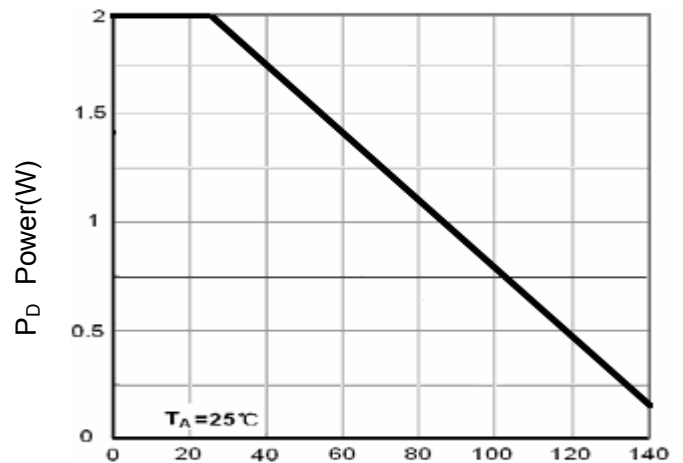
**Figure 5 Gate Charge**



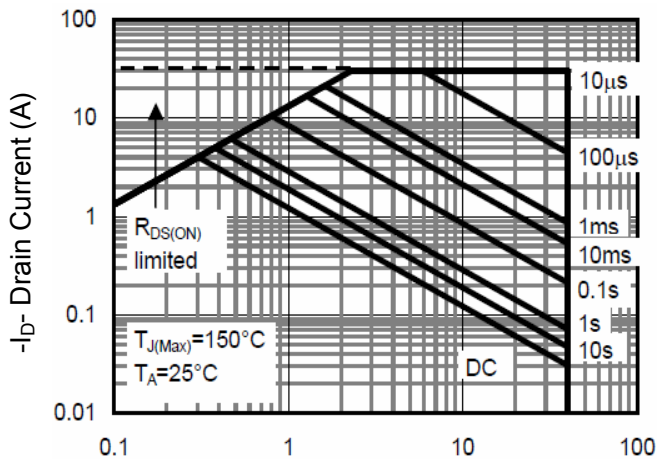
**Figure 6 Source- Drain Diode Forward**



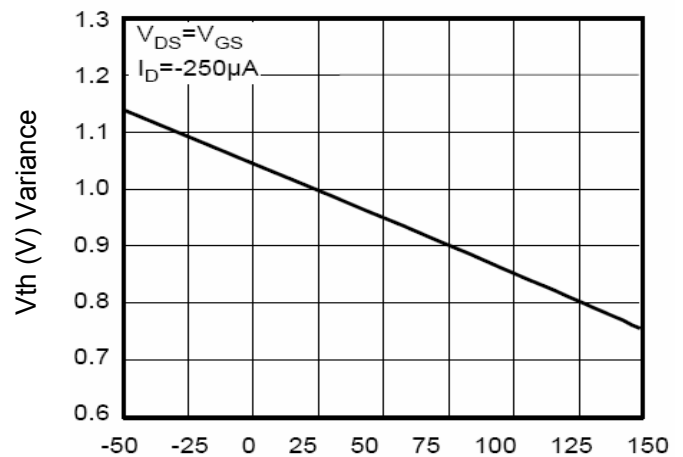
-Vds Drain-Source Voltage (V)  
**Figure 7 Capacitance vs Vds**



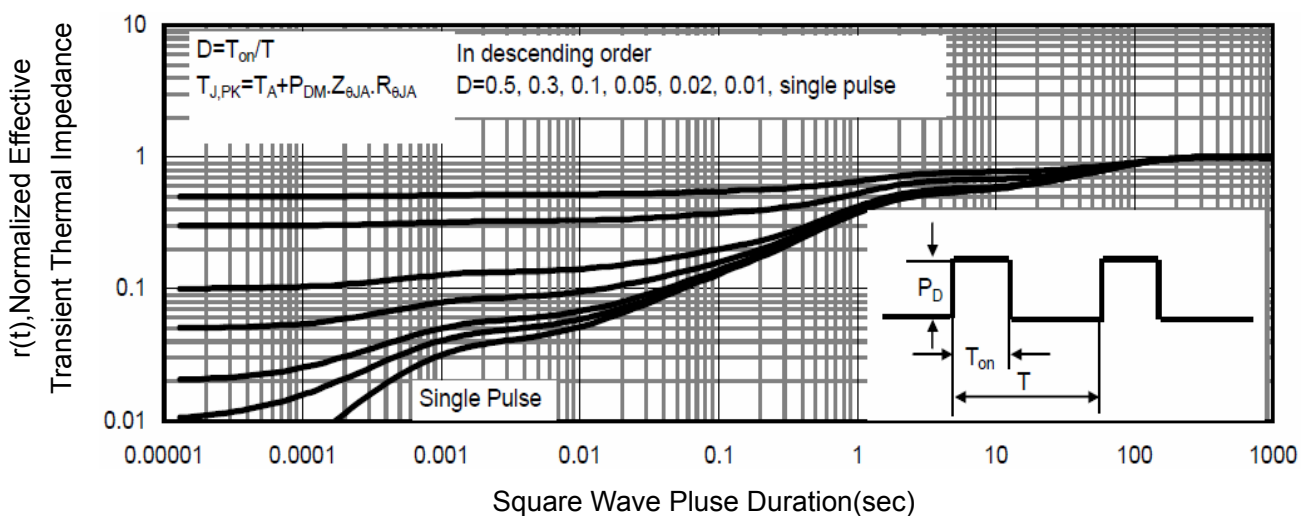
TJ-Junction Temperature(°C)  
**Figure 9 Power Dissipation**



-Vds Drain-Source Voltage (V)  
**Figure 8 Safe Operation Area**



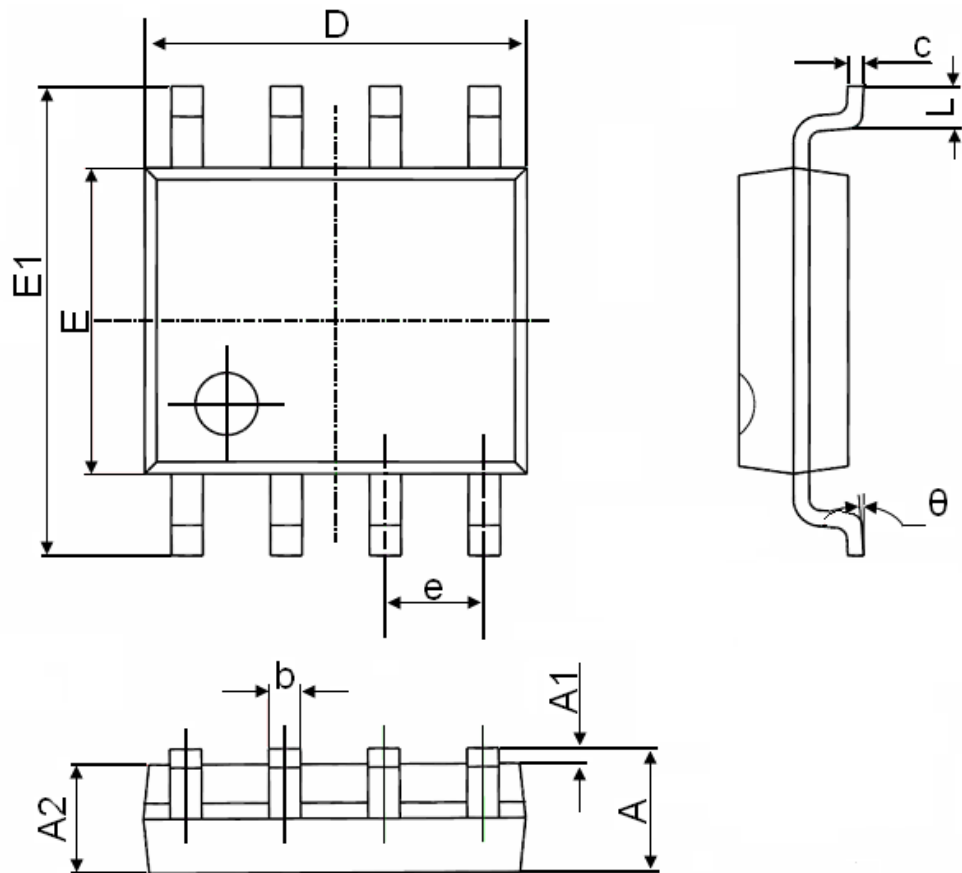
TJ-Junction Temperature(°C)  
**Figure 10 VGS(th) vs Junction Temperature**



**Figure 11 Normalized Maximum Transient Thermal Impedance**



## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°

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